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December 2014

FQPF9P25YDTU

P-Channel QFET® MOSFET

-250 V, -6 A, 620 $m\Omega$

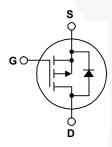
Description

produced using Fairchild Semiconductor's proprietary planar stripe and DMOS technology. This advanced MOSFET technology has been especially tailored to reduce on-state resistance, and to provide superior switching performance and high avalanche energy strength. These devices are suitable for switched mode power supplies, audio amplifier, • 100% Avalanche Tested DC motor control, and variable switching power applications.

Features

- This P-Channel enhancement mode power MOSFET is -6 A, -250 V, $R_{DS(on)}$ = 620 m Ω (Max.) @ V_{GS} = -10 V,
 - Low Gate Charge (Typ. 29 nC)
 - Low Crss (Typ. 27 pF)





Absolute Maximum Ratings T_C = 25°C unless otherwise noted.

Symbol	Parameter		FQPF9P25YDTU	Unit		
V _{DSS}	Drain-Source Voltage		-250	V		
I _D	Drain Current - Continuous (T _C = 25°C)		-6.0	Α		
	- Continuous (T _C = 100°C)		-3.9	А		
I _{DM}	Drain Current - Pulsed	(Note 1)	-24	A		
V _{GSS}	Gate-Source Voltage		± 30	V		
E _{AS}	Single Pulsed Avalanche Energy	(Note 2)	650	mJ		
I _{AR}	Avalanche Current	(Note 1)	-6.0	Α		
E _{AR}	Repetitive Avalanche Energy	(Note 1)	5.0	mJ		
dv/dt	Peak Diode Recovery dv/dt	(Note 3)	-5.5	V/ns		
P_{D}	Power Dissipation (T _C = 25°C)		50	W		
	- Derate above 25°C		0.4 W/°			
T _J , T _{STG}	Operating and Storage Temperature Range		-55 to +150	°C		
T _L	Maximum lead temperature for soldering, 1/8" from case for 5 seconds.		300	°C		

Thermal Characteristics

Symbol	Parameter	FQPF9P25YDTU	Unit	
$R_{\theta JC}$	Thermal Resistance, Junction-to-Case, Max.	2.5	°C/W	
$R_{\theta JA}$	Thermal Resistance, Junction-to-Ambient, Max.	62.5	°C/W	

Packag	je Marki	ng and Ord	ering lı	nforma	ation						
Part Number FQPF9P25YDTU		Top Mark	Pack	Package Packing Method TO-220F (-formed) Tube		Reel	Size	Tape Wi	dth	Quantity	
		FQPF9P25				N/A		N/A		50 units	
Electric	cal Chai	racteristics	T _C = 25°C	C unless other	erwise noted.						
Symbol		Parameter			Test Conditions		Min.	Тур.	Max	. Unit	
Off Cha	aracterist	ice									
BV _{DSS}		rce Breakdown Vol	tane	V _{CC} = 0	V, I _D = -250 μA		-250		_	V	
ΔBV _{DSS}	Breakdown Voltage Temperature					200			•		
/ ΔT _J		Coefficient			I_D = -250 μA, Referenced to 25°C			-0.2		V/°C	
I _{DSS}	Zana Oaka Walkana Busin Oursent			V _{DS} = -250 V, V _{GS} = 0 V					-1	μА	
	Zero Gale	Zero Gate Voltage Drain Current		V _{DS} = -200 V, T _C = 125°C					-10	μΑ	
I _{GSSF}	Gate-Body	/ Leakage Current,	Forward	rd $V_{GS} = -30 \text{ V}, V_{DS} = 0 \text{ V}$					-100	nA	
I _{GSSR}	Gate-Body	/ Leakage Current,	Reverse	$V_{GS} = 3$	80 V, V _{DS} = 0 V				100	nA	
On Cha	ıracteristi	ics									
V _{GS(th)}		shold Voltage		V _{DS} = V	/ _{GS} , I _D = -250 μA	-/	-3.0		-5.0	V	
R _{DS(on)}	Static Drai				10 V, I _D = -3.0 A			0.48	0.62	Ω	
9 _{FS}	Forward T	Transconductance		V _{DS} = -	_S = -40 V, I _D = -3.0 A			4.8		S	
Dvnam	ic Charac	teristics		1				+	1		
C _{iss}	Input Capa			V _{DS} = -25 V, V _{GS} = 0 V,				910	1180) pF	
C _{oss}	Output Ca	Capacitance		f = 1.0 MHz			170	220	pF		
C _{rss}	Reverse T	ransfer Capacitano	e	1.0 111112				27	35	pF	
				1							
		cteristics		1							
t _{d(on)}	Turn-On D			V _{DD} = -	V_{DD} = -125 V, I_{D} = -9.4 A, R_{G} = 25 Ω			20	50	ns	
t _r	Turn-On R			$R_{G} = 25$				150	310	ns	
t _{d(off)}	Turn-Off D	•						45	100	ns	
t _f	Turn-Off F				(1)	10le 4)		65	140	ns	
Q_g	Total Gate			V_{DS} = -200 V, I_{D} = -9.4 A, V_{GS} = -10 V (Note 4)				29	38	nC	
Q_{gs}	Gate-Sour	ce Charge						7.6		nC	
Q _{gd}	Gate-Drain	n Charge				lote 4)	/	14		nC	
Droin C	'auraa Di	ada Charastar	iotico c	ad Mass	imum Batinas						
	1	ode Character							-6.0	Λ	
I _S		Continuous Drain-Source Diode Forward Current Pulsed Drain-Source Diode Forward Current					-6.0				
I _{SM}									-24	A	
V _{SD}		rce Diode Forward	voltage		V, I _S = -6.0 A			100	-5.0		
t _{rr}		Recovery Time			0 V, I _S = -9.4 A, = 100 A/μs			190		ns	
Q_{rr}	Reverse R	Recovery Charge		uiF / ul	- 100 Ανμδ			1.45		μС	

Q_{rr}

- 1. Repetitive rating : pulse-width limited by maximum junction temperature.
- 2. L = 28.9 mH, I $_{AS}$ = -6.0 A, V $_{DD}$ = -50 V, R $_{G}$ = 25 Ω , starting T $_{J}$ = 25°C. 3. I $_{SD}$ ≤ -9.4 A, di/dt ≤ 300 A/ μ s , V $_{DD}$ = BV $_{DSS}$, starting T $_{J}$ = 25°C. 4. Essentially independent of operating temperature.

Typical Characteristics

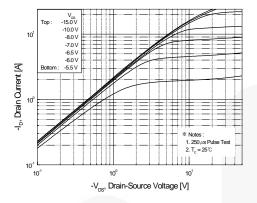


Figure 1. On-Region Characteristics

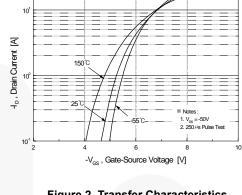


Figure 2. Transfer Characteristics

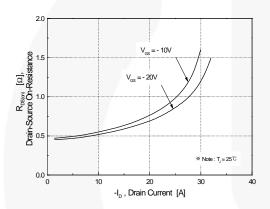


Figure 3. On-Resistance Variation vs. **Drain Current and Gate Voltage**

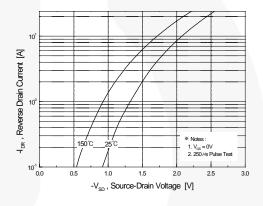


Figure 4. Body Diode Forward Voltage Variation vs. Source Current and Temperature

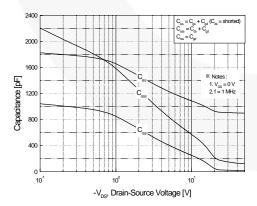


Figure 5. Capacitance Characteristics

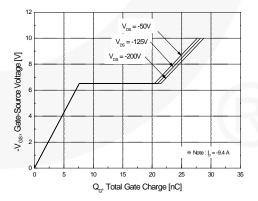
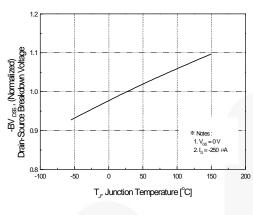


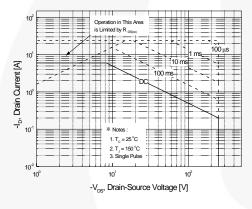
Figure 6. Gate Charge Characteristics



Typical Characteristics (Continued)

Figure 7. Breakdown Voltage Variation vs. Temperature

Figure 8. On-Resistance Variation vs. Temperature



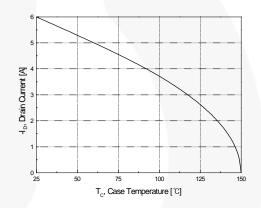


Figure 9. Maximum Safe Operating Area

Figure 10. Maximum Drain Current vs. Case Temperature

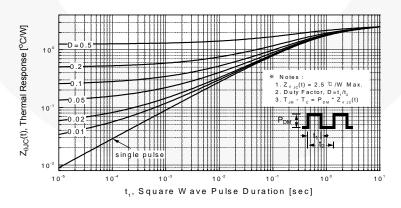


Figure 11. Transient Thermal Response Curve

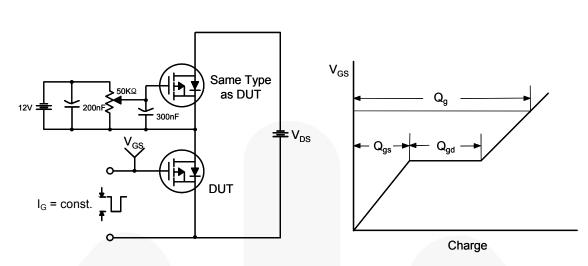


Figure 12. Gate Charge Test Circuit & Waveform

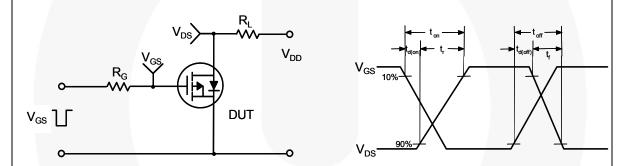


Figure 13. Resistive Switching Test Circuit & Waveforms

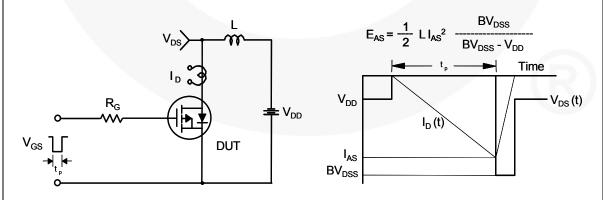
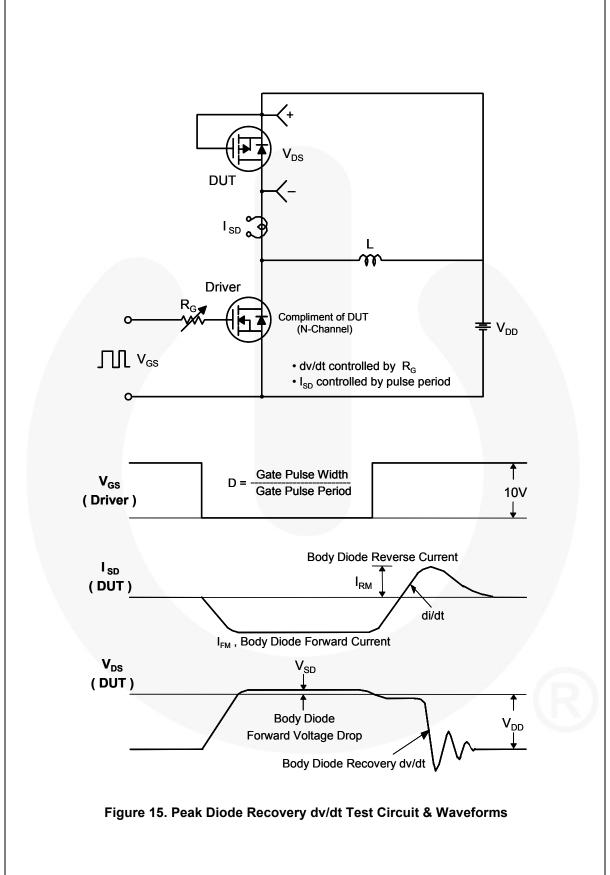
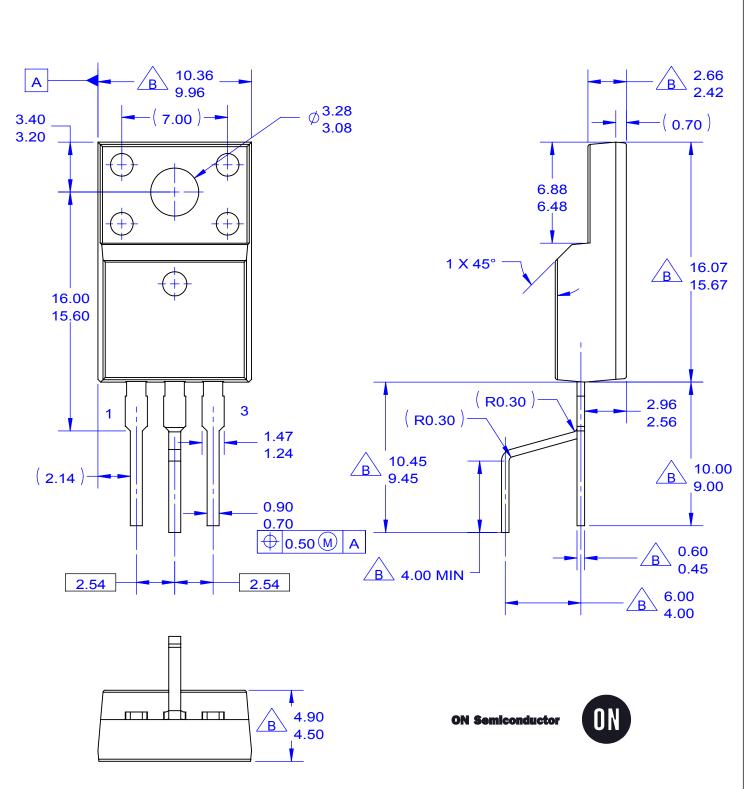


Figure 14. Unclamped Inductive Switching Test Circuit & Waveforms





NOTES:

- A. EXCEPT WHERE NOTED CONFORMS TO
- EIAJ SC91A.

 B DOES NOT COMPLY EIAJ STD. VALUE.
- C. ALL DIMENSIONS ARE IN MILLIMETERS.
- D. DIMENSIONS ARE EXCLUSIVE OF BURRS, MOLD FLASH AND TIE BAR PROTRUSIONS.
- E. DIMENSION AND TOLERANCE AS PER ASME Y14.5-1994.
- F. DRAWING FILE NAME: TO220Q03REV2

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